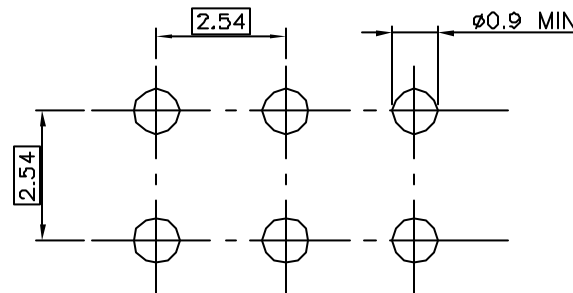
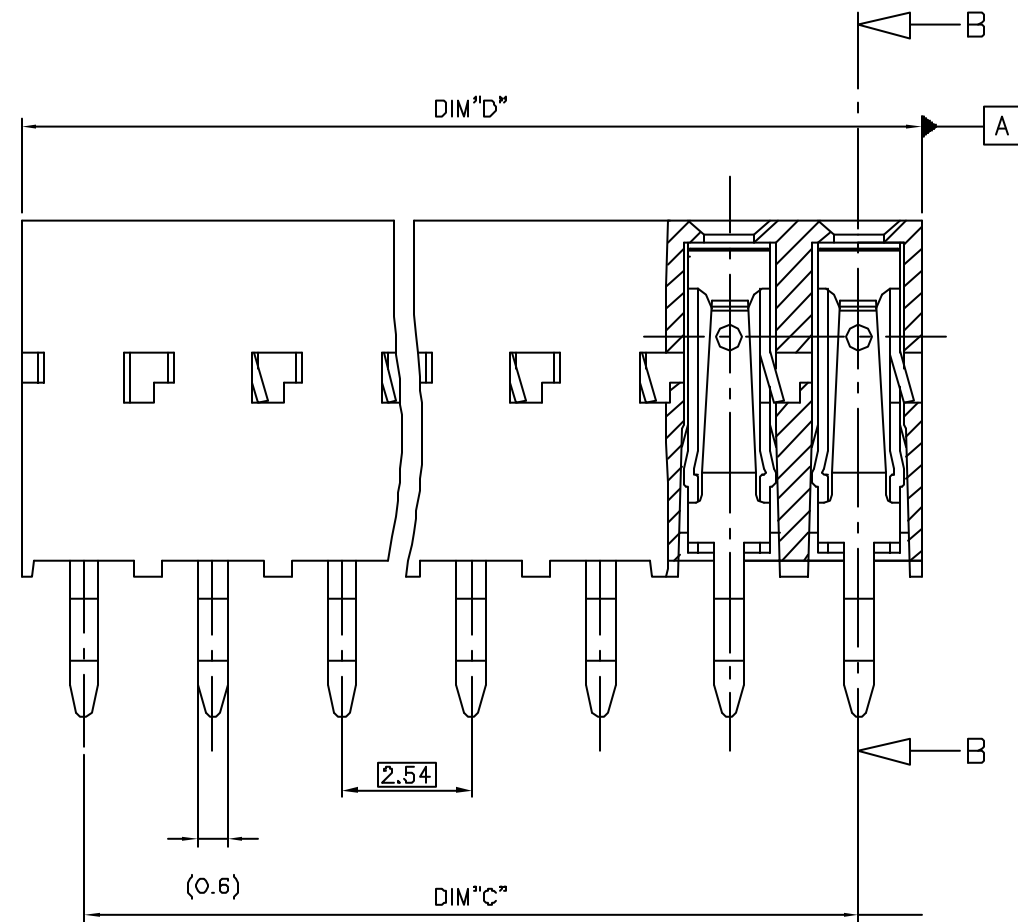


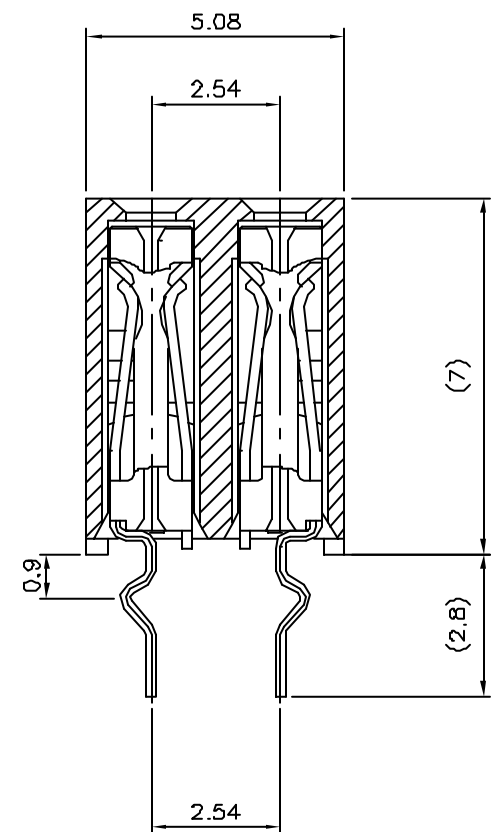
VIEW A



RECOMMENDED HOLE PATTERN



SECTION A-A



SECTION B-B

PRODUCT NUMBER	NUMBER OF POS.	DIM "C"	DIM "D"
71998-Y02(H)(LF)	2 x 02	2.54	5.00
71998-Y03(H)(LF)	2 x 03	5.08	7.54
71998-Y04(H)(LF)	2 x 04	7.62	10.08
71998-Y05(H)(LF)	2 x 05	10.16	12.62
71998-Y06(H)(LF)	2 x 06	12.70	15.16
71998-Y07(H)(LF)	2 x 07	15.24	17.70
71998-Y08(H)(LF)	2 x 08	17.78	20.24
71998-Y09(H)(LF)	2 x 09	20.32	22.78
71998-Y10(H)(LF)	2 x 10	22.86	25.32
71998-Y13(H)(LF)	2 x 13	30.48	32.94

WHEN NEEDED, SUFFIX LETTER "LF" INDICATES THE PRODUCT IS RoHS COMPATIBLE, SEE NOTE 4

WHEN NEEDED, SUFFIX LETTER "H" INDICATES IT'S A HIGH TEMPERATURE PRODUCT SEE NOTE 2

NOTES:

- MATERIAL HOUSING: THERMOPLASTIC POLYESTER 30% GLASS FILLED, COLOUR BLUE. FLAME RETARDANT PER UL-94 CATEGORY V0.
- MATERIAL HOUSING: HIGH TEMPERATURE THERMOPLASTIC 30% GLASS FILLED, COLOUR GREY. FLAME RETARDANT PER UL-94 CATEGORY V0.
- MATERIAL TERMINAL: PHOSPHOR BRONZE EXTRA HARD.
- RoHS COMPATIBLE PRODUCT SPECIFICATIONS
 - PLATING:
 - "LF" MEANS THE PRODUCT IS LEAD-FREE, 2µm MINIMUM MATTE TIN OVER 1.27µm MINIMUM NICKEL UNDERPLATE.
 - MANUFACTURING PROCESS COMPATIBILITY
 - THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C ±5°C SOLDER BATH TEMPERATURE FOR 5 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.6mm MIN THICK CIRCUIT BOARD.
- LABELING:
 - MEETS PACKAGING SPECS AS PER GS-14-920
- LEGAL STATEMENT: SEE GS-22-008

71998-4XX(H)LF	5µm Sn	Sn
71998-3XX(H)LF	0.76 µm GOLD	Sn
71998-4XX(H)	5µm SnPb	SnPb
71998-3XX(H)	0.76 µm GOLD	SnPb
PLATING CODE	CONTACT AREA	SOLDER TAIL
PLATING THICKNESS OVER 1.27µm Ni		

mat'l. code	surface	tolerance	projection	product family
SEE NOTES	ISO 1302	ISO 416 ISO 1101		DX VCC DR
Ltr	ecr	na	dr	date
B	F40794	DLE	94.03.08	angles
C	F04-0347	DLE	04.11.17	Linear
D	F06-0234	DLE	05.08.24	±2°
E	F08-0137	DLE	06.02.27	dr
F	F08-0204	DLE	08.08.20	enr
G	F07-0188	DLE	07.06.31	chr
H	F07-0271	LMU	07.12.06	app
sheet index	revision	sheet		

FCJ
KINKED LEGS
71998
CUSTOMER Drawing